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H. Nishikawa, and K. Niwa - Osaka University, Ibaraki, Osaka Japan

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S. Jain[a], D.C. Whalley[a], M. Cottrill[a], H. Kristiansen[b,c], K.Redford[c], S.Helland[b], T. Helland[b], Erik Kalland[b], C. Liu[a] - [a]Loughborough University, Loughborough, UK - [b]Mosaic Solutions AS, Skjetten, Norway

Session ThA3 : Molding, filling and finishing

Chairs : Eric Saugier (ST Microelectronics), Martin Schneider Ramelow (Fraunhofer IZM)

94 - Evaluation of the Hot Embossing Technology for the Fabrication of Resonant Circuits as Instrument Visualization Method for Interventional Magnetic Resonance Imaging

Markus Detert, Mandy Kaiser, Stephan Friesecke, Georg Rose, and Bertram Schmidt - Otto-von-Guericke-University Magdeburg, Institute of Micro- and Sensor Systems, Magdeburg, Germany

95 - Epoxy Molding compounds for High Temperature Applications

A. Mavinkurve, L. Goumans* and J. Martens** - * NXP Semiconductors, Nijmegen, The Netherlands - ** NXP Semiconductors, Hamburg, Germany*

96 - Copper Filled Polyurethane Based Electrically Conductive Adhesive with Improved Mechanical Strength

Li-Ngee Ho **and Hiroshi Nishikawa* - * Osaka University, Ibaraki, Osaka, Japan. - ** University Malaysia Perlis, Arau, Perlis, Malaysia.*

97 - Reliable filling of through vias with silver based conductive adhesives in flexible PEN substrates using low-cost optimized stencil printing methods

Mária Péter, Daan van den Ende*, Bart van Remoortere* ***, Steven van Put**, Tomas Podprocky**, Anja Henckens***, Jeroen van den Brand - *Holst Centre, TNO, Eindhoven, The Netherlands - **IMEC-CMST, Ghent, Belgium - ***Henkel Electronic Materials NV, Westerlo, Belgium*

98 - ENEPIG finish: An Alternative Solution for Space Printed Circuit Boards (PCB)

*A. Chaillot[*], N. Venet[**], P-E. Tegehall[***], J. Hokka[****], J-L. Lortal[*****] - [*]ASTRIUM, ** THALES ALENIA SPACE, [***]IVF, [****]ESA, [*****]CNES*

Session ThP1 : WLP and PoP : Innovations and processes

Chairs : Yann Lamy (CEA- LETI), Jean Christophe Crébier (CMP)

99 - Evolution of Wafer Level Packaging for Mobile Devices

John Hunt [1], Adren Hsieh [2], Christophe Zinck [3] - [1] ASE Group, US - [2] ASE Group, Kaohsiung - [3] ASE Group, Europe

100 - Challenges with Manufacturability of Package on Package (PoP)

Petri Savolainen, Craig Hillman, Cheryl Tulkoff, and Greg Caswell - DfR Solutions, Beltsville, MD, USA*

101 - New approach for assessment of Dielectric Layer Adhesion Strength, demonstrated on eWLB FO-WLP Interfaces

Jorge Teixeira, Raquel Pinto, Abel Janeiro, Paulo Cardoso, Mário Ribeiro ***Eoin O'Toole*** *- NANIUM S.A, Vila do Conde, Portugal*

102 - Wafer-Level Underfill selection protocole for 3D stacks

Amandine Jouve[1], Arnaud Garnier[1], Sylvain Joblot[2], Guillaume Riado[2], Rémi Franiatte[1], Alisée Taluy[2,3], Séverine Cheramy[1] - [1] CEA, LETI, MINATEC campus, 17 rue des Martyrs, 38054 GRENOBLE Cedex 9, France. - [2] STMicroelectronics, 850 rue Jean Monnet, F-38920 Crolles Cedex, France. - [3] G2ELAb, University of Grenoble 1, BP166, 38042 Grenoble Cedex 9, France.*

Session ThP2 : : Reliability for space applications

Chairs : Hervé Ribot (CEA-LETI), Brigitte Braux (Astrium)

103 - Probabilistic Design for Reliability (PDfR) in Space Electronics and Photonics: a Change of Vision.

A. Bensoussan - Thales Alenia Space France, Toulouse, France

104 - Board Level Reliability Testing of Hermetic Packages Equipped with High-Rel Interconnection Solutions and Dedicated to Space Applications

Olivier Gaillard - e2v semiconductors, St-Egrève, France

105 - Verification of an LTCC Packaging Technology on Board of the ongoing TET-1 Satellite Mission

Reinhard Kulke, Tobias Klein, Gregor Möllenbeck, Carsten Günner and Matthias Rittweger - IMST GmbH, Kamp-Lintfort, Germany

106 - Coupling experimental and modelling results for device failure anticipation

Diane Ecoiffier, Pierre Vernhes - Insidix, Seyssins, France

Session ThP3 : MEMS Process and Manufacturing

Chairs : Philippe Soussan (IMEC), Alan Mathewson (Tyndall)